

TD Seal RT Application Procedure

- 1. Clean the surface to remove any dust, oils, or contaminants.
- 2. Repair flaws: Fill larger voids using 3M 08115 panel bonding adhesive or equivalent
- 3. Clean the surface again with a product compatible with the printed material.
- 4. Final wipe-down: Use a 50/50 mixture of isopropyl alcohol (IPA) and distilled water.
- 5. Stir TD Seal HT thoroughly do not shake to avoid introducing air bubbles.
- 6. **Catalyze**: Mix TD Seal HT with **1.5%–2% MEKP 925H** (or equivalent) and stir thoroughly. We use a dye in the MEKP to visually identify when it has been mixed properly.
- 7. **Prep the surface**: Blow off loose debris and wipe with a tack cloth.
- 8. Spray application:
 - Maintain a spray distance of 6–8 inches from the surface.
 - Use air pressure of 20–25 psi.
 - o Gun tip 1.8mm
- 9. Application by brush or roller is not recommended.
- 10. Apply 4 wet-on-wet passes, each at 0.003 inches, for a total build-up of 0.012 inches.
- 11. Inspect the surface: If imperfections remain, spot-fill using a dabber.
- 12. Apply an additional 0.012 inches using 4 more wet-on-wet passes.
- 13. **Heat cure**: Maintain at **120°F for 30 minutes**. The coating will still be soft but hard enough to sand
- 14. Sand and buff as needed using the following grit sequence: 400, 600, 800, 1500, and 2000 (US standard).
- 15. **Polish** using compounds in sequence (we've used in the past):
 - o 3M 36060
 - o 3M 06064
 - o 3M 06068

Currently we use

- o 3D Hybrid Compound and Polish stages 1 to 3
- o 3D ACA 500 Alpha Ceramic Alumina
- 16. Post-cure the tool at 140°F for 2 hours. Shore D hardness rating 90

Using Mold Release

- 1. Apply one coat of mold release to the finished surface
- 2. Apply masking tape to areas where sealing tape will be used
- 3. Apply appropriate mold release, for the application, over the mold surface up to the edge of the tape
- 4. Remove masking tape and apply sealant tape